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PATENT
Attorney Docket No. 98124x205487

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Group Art Unit: 1765

Application No. 09/636,161

Examiner: L. Umez-Eronini

Filed: August 10, 2000

For: POLISHING SYSTEM AND
METHOD OF ITS USE

PRELIMINARY AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

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FEB 27 2002
TC 1700

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.

AMENDMENTS

IN THE SPECIFICATION:

Replace the paragraph beginning at page 1, line 13, with:

Integrated circuits are made up of millions of active devices formed in or on a substrate, such as a silicon wafer. The active devices are chemically and physically connected into a substrate and are interconnected through the use of multilevel interconnects to form functional circuits. Typical multilevel interconnects comprise a first metal layer, an interlevel dielectric layer, and sometimes a third and subsequent metal layer. Interlevel dielectrics, such as doped and undoped silicon dioxide (SiO₂) and/or low- κ dielectrics, are used to electrically isolate the different metal layers.

Replace the paragraph beginning at page 5, line 11, with:

The polishing additive can be any suitable phosphorous-containing compound.

A2
Suitable phosphorous-containing compounds include, for example, phosphates (e.g., pyrophosphates, tri-phosphates, condensed phosphates), phosphonic acids (e.g., mono-phosphonic acids, di-phosphonic acids, tri-phosphonic acids, poly-phosphonic acids), and salts of phosphonic acids. Preferred phosphorous-containing compounds include, for

In re Appln. of Wang et al.
Application No. 09/636,161



CERTIFICATE OF MAILING

I hereby certify that this PRELIMINARY AMENDMENT (along with any documents referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date: January 17, 2002

A handwritten signature in black ink, appearing to read "John K. H.", is written over a horizontal line.

205487 Prelim.Amend